ABSTRACT OF THE DISCLOSURE

Electric conductor patterns having inner leads arranged at a pitch of not larger than 60 μm are formed on a front surface of an insulating layer of a tape carrier for TAB. A reinforcing layer of stainless steel foil is formed on a rear surface of the insulating layer so as to be extend along a lengthwise direction at opposite side edge portions in a widthwise direction of the insulating layer. Accordingly, both dimensional accuracy and positional accuracy can be improved at the time of carrying the tape carrier for TAB or at the time of mounting and bonding electronic parts though the insulating layer can be formed so as to be thin.